**Celsee, Inc.**

**Genesis V2 Daughter PCB – PN 10000387 Rev. 2 03/29/2019**

**Fabrication Specification**

**Brian Boniface, Software and Electrical Engineer**

The following table identifies the fabrication specification for the PREP400 PCB:

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| **Attribute** | **Specification** |
| Board Size | 10.24” x 5.67” (includes rails) |
| Layers | 4 |
| Stack Order | Top Signal (Component Side), Ground, Power, Bottom Signal |
| Material Type | FR4 |
| Finished Thickness | 0.62” |
| Rout Type | Individually routed |
| Array/Panel | The PCB already includes array rails. No additional arrays required. |
| Finished Plating | Lead-free solder |
| Copper Weight | 1-oz |
| Drill | Specified in PTH and NPTH drill files. |
| Slots | No |
| Soldermask | Specified in top and bottom mask gerbers. |
| Soldermask Color | Blue |
| Silkscreen | Specified in top and bottom silk gerbers. No silk on pads. |
| Silkscreen Color | White |
| Gold Fingers | No |
| Dielectric Thickness | Use of standard dielectric stack as determined by design. |
| Impedance | No |
| RoHS | Yes |
| ITAR | No |
| Board Thickness Tolerance | +/- 10% |
| Dimensional Tolerance | +/- 10 mils |
| Inspection Criteria | IPC Class II |